

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Table I: Corrected the max limit for the test +I _{CC} , changed from "300 μA" to "800 μA". Table I: Added additional test conditions for the Switch ON resistance test. Updated footnotes in section 1.5. Made clarifications to table IIIA and table IV. Updated section 4.3.5. -sld	13-10-01	Charles F. Saffle

REV																				
SHEET																				
REV	A	A	A	A	A															
SHEET	15	16	17	18	19															
REV STATUS OF SHEETS	REV			A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	
	SHEET			1	2	3	4	5	6	7	8	9	10	11	12	13	14			

PMIC N/A	PREPARED BY Steve L. Duncan	<p align="center">DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 http://www.landandmaritime.dla.mil/</p>																		
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p align="center">THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p align="center">AMSC N/A</p>	CHECKED BY Greg Cecil																			
	APPROVED BY Charles F. Saffle	<p align="center">MICROCIRCUIT, CMOS, LINEAR, ANALOG MULTIPLEXER, 8 CHANNEL, +3.3 TO +5 VOLT, MONOLITHIC SILICON</p>																		
	DRAWING APPROVAL DATE 13-03-27																			
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1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	See figure 1	16	Flat package with formed leads

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

1.3 Absolute maximum ratings. 1/

Supply voltage (V_{CC}).....	+7.0 V dc
Digital input overvoltage range:	
V_{EN}, V_A (device types 01 and 02).....	(< $V_{CC} + .4$)V, (> GND - .4)V
V_{SH}, V_A (device type 03).....	(< $V_{CC} + .4$)V, (> GND - .4)V
Analog input overvoltage range.....	(< $V_{CC} + .4$)V, (> GND - .4)V
Power dissipation (P_D):	
Device types 01, 02, and 03.....	200 mW
Thermal resistance junction-to-case (θ_{JC}).....	5 °C/W
Storage temperature.....	-65°C to +150°C
Lead temperature (soldering, 10 seconds).....	+300°C

1.4 Recommended operating conditions.

Supply voltage range (V_{CC}).....	+3.0 V to +5.5 V dc
Logic low level voltage :	
V_{EN}, V_A (device types 01 and 02).....	0.3 V_{CC}
V_{SH}, V_A (device type 03).....	0.3 V_{CC}
Logic high level voltage:	
V_{EN}, V_A (device types 01 and 02).....	0.7 V_{CC}
V_{SH}, V_A (device type 03).....	0.7 V_{CC}
Case operating temperature range (T_C).....	-55°C to +125°C

1.5 Radiation features. 2/

Maximum Total Ionizing Dose (TID) ..(dose rate = 50 - 300 rad(Si)/s):	
In accordance with MIL-STD-883, method 1019, condition A.	1 Mrad(Si)
Enhanced Low Dose Rate Sensitivity (ELDRS).....	<u>3/</u>
Single Event Latchup (SEL).....	> 100 MeV-cm ² /mg <u>4/</u>
Neutron Displacement Damage (> 1 x 10 ¹⁴ neutrons/cm ²).....	<u>3/</u>

1/ Stresses above the absolute maximum ratings may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

2/ See section 4.3.5 for the manufacturer's radiation hardness assurance analysis and testing.

3/ Not tested, Immune by 100 percent CMOS technology.

4/ Single Event Latchup (SEL) immunity is accomplished by double, fully enclosing, guard rings in the CMOS design layout. The guard rings eliminate the parasitic pnpn structure that is responsible for latchup in CMOS circuits. This limit is guaranteed by design or process, but not tested.

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2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATIONS

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
 MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
 MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 shall include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. The manufacturer may eliminate, modify or optimize the tests and inspections herein, however the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class. In addition, the modification in the QM plan shall not affect the form, fit, or function of the device for the applicable device class.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Truth table(s). The truth table(s) shall be as specified on figure 3.

3.2.4 Switching test waveform(s). The switching test waveform(s) shall be as specified on figure 4.

3.2.5 Block diagram. The block diagram(s) shall be as specified on figure 5.

3.2.6 Radiation exposure circuits. The radiation exposure circuits shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

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3.5 Marking of device(s). Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked.

3.6 Data. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DLA Land and Maritime -VA) upon request.

3.7 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DLA Land and Maritime -VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.

3.8 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{CC} = +5 V unless otherwise specified	Group A subgroups	Device types	Limits		Unit	
					Min	Max		
Supply currents <u>1/</u>	+I _{CC}	$\overline{EN} = 0.3 V_{CC}$	1,2,3	01	10	800	μA	
				02	0.5	5	mA	
				03	10	100	μA	
	+I _{SBY}	$\overline{EN} = 0.7 V_{CC}$	1,2,3	01	10	200	μA	
				02	10	500		
Address input <u>1/</u> currents	I _{AL}	V _A = 0.3 V _{CC}	1	All	-5	5	nA	
			2	All	-50	50		
	I _{AH}	V _A = 0.7 V _{CC}	1	All	-5	5	nA	
			2	All	-50	50		
Enable input <u>1/</u> current	I _{ENL}	V _{EN} = 0.3 V _{CC}	1	01,02	-5	5	nA	
			2		-50	50		
	I _{ENH}	V _{EN} = 0.7 V _{CC}	1	01,02	-5	5	nA	
			2		-50	50		
Sample-and-Hold input current	I _{SH}	V _{SH} = 0.3 V _{CC}	1	03	-5	5	nA	
			2		-50	50		
		V _{SH} = 0.7 V _{CC}	1		-5	5		
			2		-50	50		
Input leakage current (CH0 - CH7) <u>1/</u>	I _{INLK5}	V _{IN} = +5 V, V _{EN} = 0.7 V _{CC} , output and all unused MUX inputs under test = 0 V	1	01,02	-5	5	nA	
			2		-50	50		
			V _{IN} = +5 V, V _{SH} = 0.7 V _{CC}	1	03	-5	5	
				2		-50	50	
	I _{INLK0}	V _{IN} = 0 V, V _{EN} = 0.7 V _{CC} , output and all unused MUX inputs under test = +5 V	1	01	-5	5	nA	
			2		-50	50		
Output leakage current <u>1/</u>	I _{OUTLK}	V _{OUT} = +5 V, V _{EN} = 0.7 V _{CC} , All inputs grounded except channel being tested	1	01	-5	5	nA	
			2		-50	50		
		Tri-state, V _{EN} > 0.7 V _{CC}	1	02	-5	5		
			2		-50	50		

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{CC} = +5 V unless otherwise specified	Group A subgroups	Device types	Limits		Unit
					Min	Max	
Output on voltage	V _{ON1}	V _{IN} = +5 V, R _L = 10 kΩ	1,2,3	02,03	4.8	5.1	V
	V _{ON2}	V _{IN} = +5 V, R _L = 1 kΩ			4.35	4.65	
	V _{ON3}	V _{IN} = +3.3 V, R _L = 10 kΩ			3.2	3.4	
Input load capacitance	C _{IN}		1,2,3	03		35	pF
Switch ON <u>1</u> / resistance	R _{DSON}	V _{IN} = 0 V, V _{EN} = 0.3 V _{CC} , I _{OUT} = +1 mA	1	01		750	Ω
			2			1000	
			3			500	
		V _{IN} = +2.5 V, V _{EN} = 0.3 V _{CC} , I _{OUT} = -0.6 mA	1		750		
			2		1000		
			3		500		
		V _{IN} = +5 V, V _{EN} = 0.3 V _{CC} , I _{OUT} = -1 mA	1		750		
			2		1000		
			3		500		
Address to output delay	t _{AHL}	R _L = 10 kΩ, C _L = 50 pF, See figure 4	9,11	01	10	150	ns
			10		10	200	
		9,10,11		02,03	1	3	μs
	t _{ALH}	R _L = 10 kΩ, C _L = 50 pF, See figure 4	9,11	01	10	150	ns
			10		10	200	
				9,10,11		02,03	1
	t _{ONEN}	R _L = 1 kΩ, C _L = 50 pF, See figure 4	9,11	01	10	150	ns
			10		10	200	
			9,10,11		02	.8	2.5
t _{OFFEN}	R _L = 1 kΩ, C _L = 50 pF, See figure 4	9,10,11	01	10	200	ns	
			02	100	350		
Droop rate	D _R	R _L = 1 kΩ, C _L = 50 pF, See figure 4	9,10,11	03		0.1	V/s
Data setup time	t _{DS}	R _L = 1 kΩ, C _L = 50 pF, See figure 4	9,10,11	03	150		ns
Data hold time	t _{DH}	R _L = 1 kΩ, C _L = 50 pF, See figure 4	9,10,11	03	150		ns
Output slew rate	t _S		9,10,11	02	1.8	4	V/μs

1/ These devices have been tested to (2 Mrad(Si)) to Method 1019, condition A of MIL-STD-883 at +25°C for these parameters to assure the requirements of RHA designator level "H" (1Mrad(Si)) are met.

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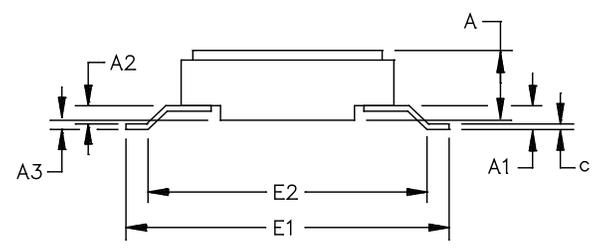
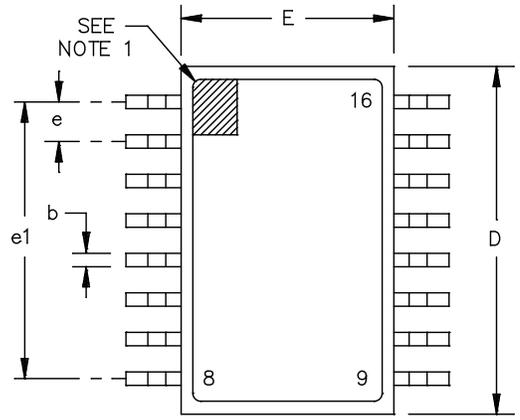
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Case outline X.



Symbol	Inches		Millimeters	
	Min	Max	Min	Max
A		.105		2.67
A1	.030 REF		0.76 REF	
A2	.017	.027	0.43	0.69
A3		.012		0.30
b	.015	.019	0.38	0.48
c	.007	.009	0.18	0.23
D		.417		10.59
e	.050 BSC		1.27 BSC	
e1	.350 BSC		8.90 BSC	
E		.300		7.62
E1	.394	.419	10.01	10.64
E2	.346 REF		8.79 REF	

NOTE:

1. Location of the pin 1 marking. The ESD symbol may be used as the pin 1 marking.
2. The U.S. preferred system of measurement is the metric SI. This item was designed using inch-pound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
3. Package and lid are electrically isolated from signal pads.
4. It is recommended that the lid and NC_GND (pin 15) be grounded to prevent ESD or static buildup.

FIGURE 1. Case outline(s).

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Device types	01 and 02	03
Case outlines	X	
Terminal number	Terminal symbol	Terminal symbol
1	V _{OUT}	V _{OUT}
2	CH7	CH7
3	CH6	CH6
4	CH5	CH5
5	CH4	CH4
6	A2	A2
7	A1	A1
8	GND	GND
9	A0	A0
10	$\overline{\text{EN}}$	S/H
11	CH0	CH0
12	CH1	CH1
13	CH2	CH2
14	CH3	CH3
15	NC_GND	NC_GND
16	V _{CC}	V _{CC}

NOTE: NC_GND should be grounded to prevent ESD or static buildup.

FIGURE 2. Terminal connections.

Truth table (CH0-CH7)				
A2	A1	A0	$\overline{\text{EN}}$ <u>1/</u>	"ON" Channel <u>2/</u>
X	X	X	H	None <u>1/</u>
L	L	L	L	CH0
L	L	H	L	CH1
L	H	L	L	CH2
L	H	H	L	CH3
H	L	L	L	CH4
H	L	H	L	CH5
H	H	L	L	CH6
H	H	H	L	CH7

1/ For device types 01 and 02 only.

2/ Between (CH0-CH7) and V_{out}.

FIGURE 3. Truth table.

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DEVICE TYPE 01

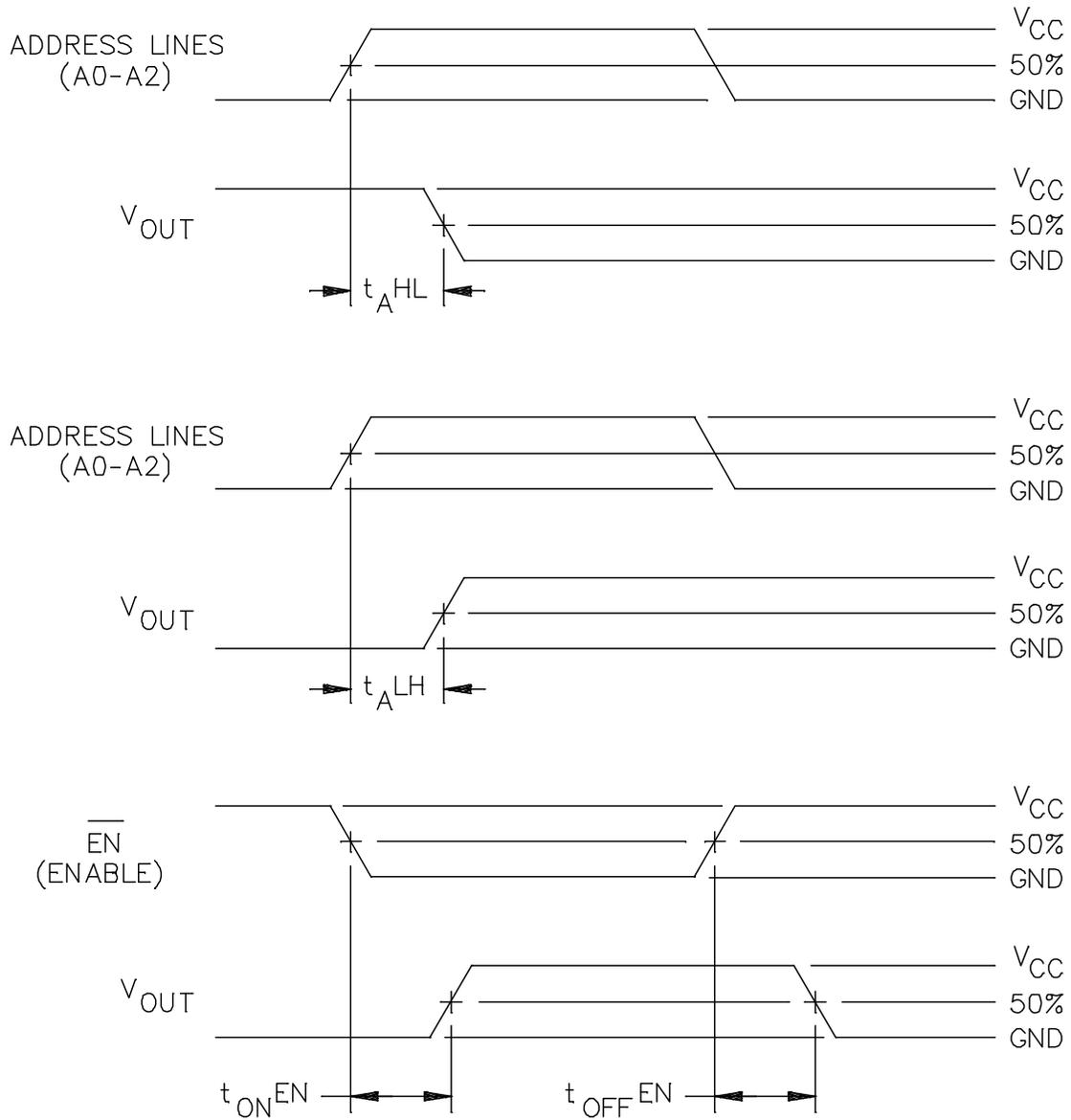


FIGURE 4. Switching test waveform(s).

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DEVICE TYPE 02

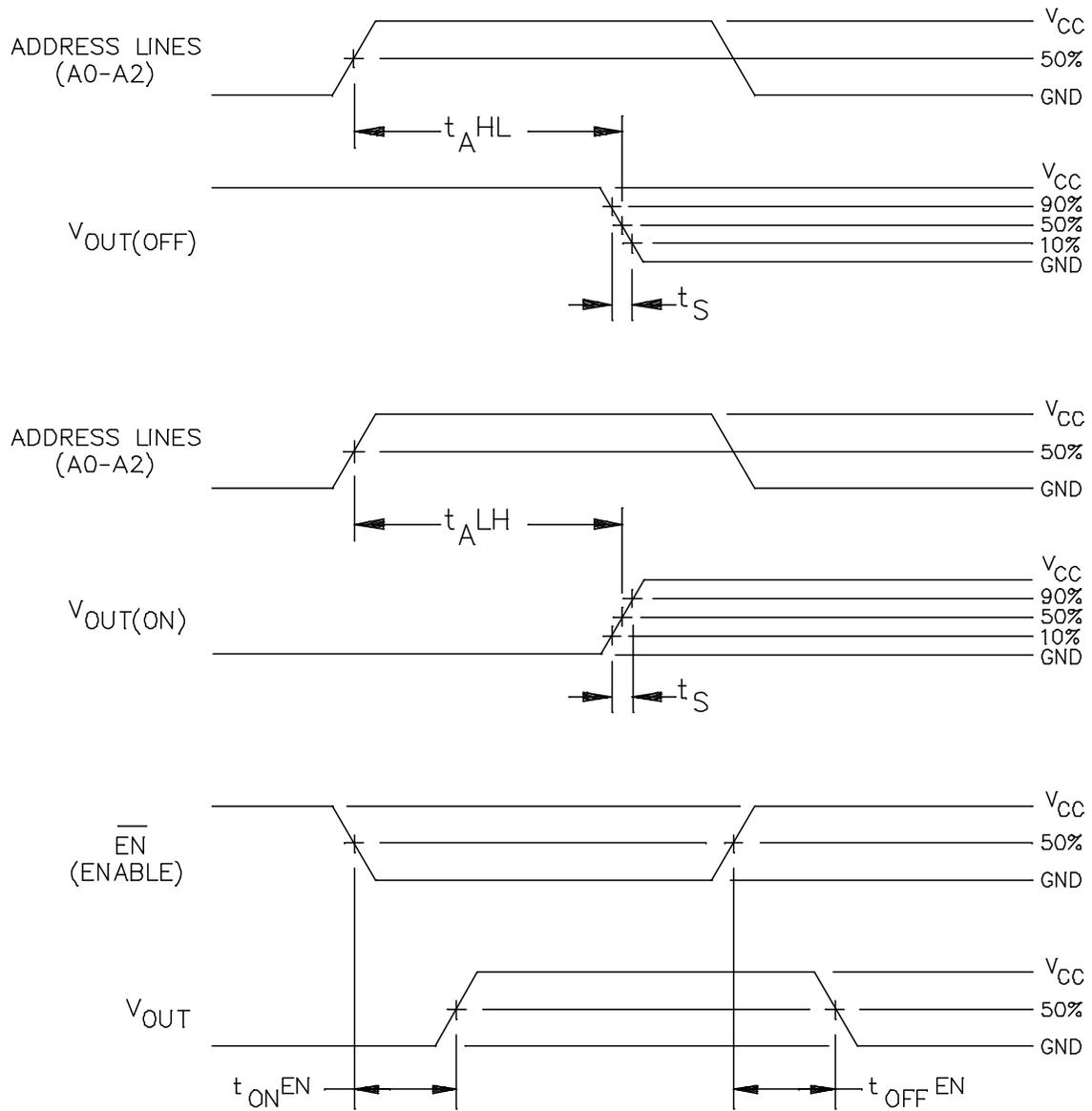


FIGURE 4. Switching test waveform(s) - Continued.

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DEVICE TYPE 03

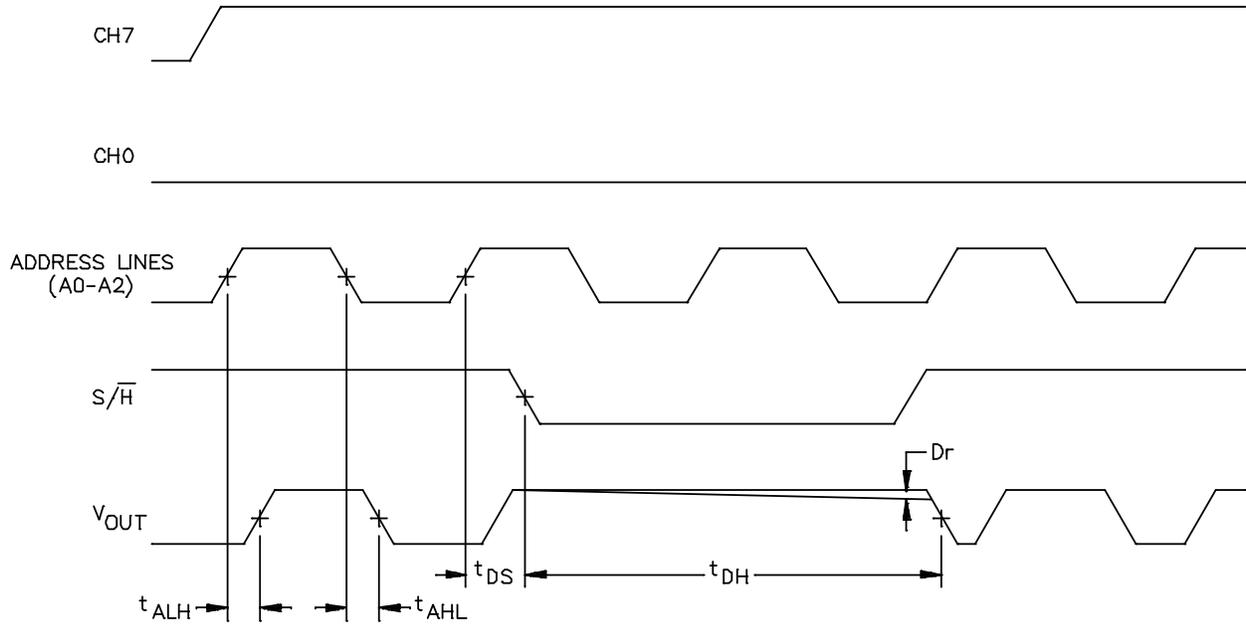
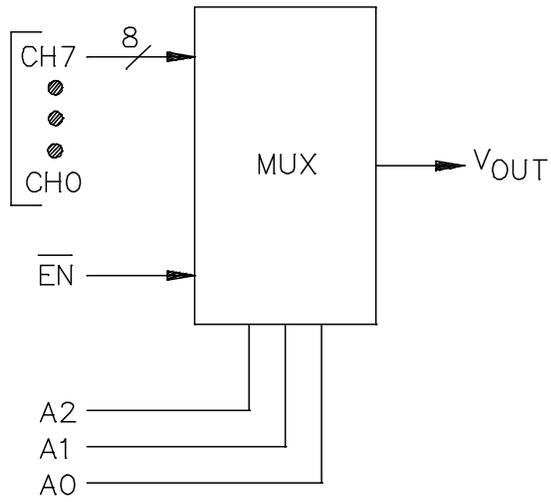


FIGURE 4. Switching test waveform(s) - Continued.

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DEVICE TYPE 01



DEVICE TYPE 02

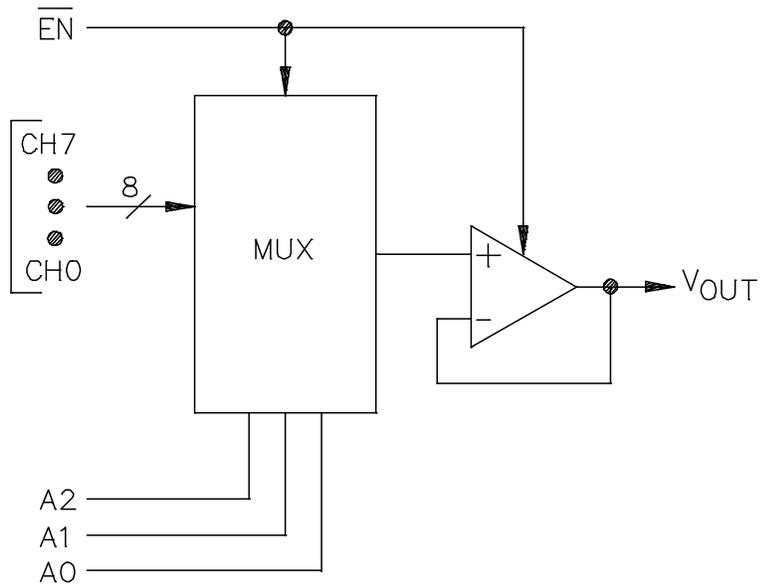


FIGURE 5. Block Diagram.

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DEVICE TYPE 03

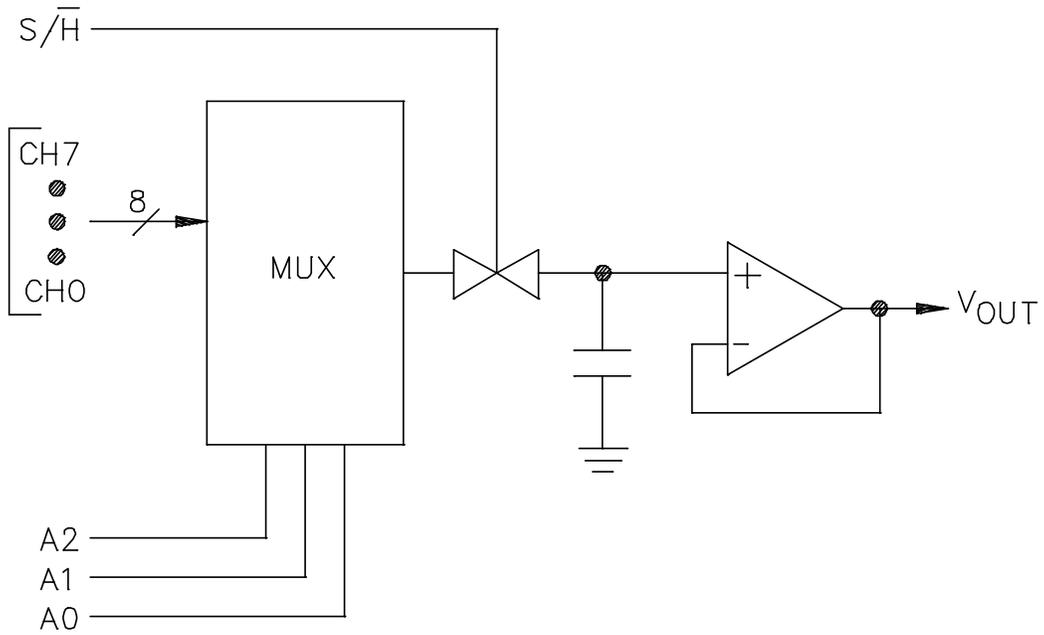


FIGURE 5. Block diagram - Continued.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	1,9
Final electrical parameters	1*,2,3,9,10,11
Group A test requirements	1,2,3,9,10,11
Group C end-point electrical parameters	1,2,3,9,10,11
End-point electrical parameters for radiation hardness assurance (RHA) devices	1

* PDA applies to subgroup 1.

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DLA Land and Maritime -VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

(2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Conformance and periodic inspections. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.

4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, 6, 7, and 8 shall be omitted.

4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

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4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DLA Land and Maritime -VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.

4.3.5. Radiation hardness assurance (RHA). RHA qualification is required only for those devices with the RHA designator as specified herein. See table IIIA and table IIIB.

Table IIIA. Radiation Hardness Assurance Method Table.

RHA method employed	Total Dose Testing RHA level "H" (1 Mrad)		Worst Case Analysis Performed No				End point electricals after total dose	
	Element Level	Hybrid Device Level	Includes temperature effects	Combines temperature and radiation effects	Combines total dose and displacement effects	End-of-life	Element Level	Hybrid device level
	(2 Mrad)	(2 Mrad) (See 4.3.5.1.1)	N/A	N/A	N/A	N/A	T _C = +25°C	T _C = +25°C

NOTES:

- X = Radiation testing done (Level)
- G = Guaranteed by design or process
- (N) = Not yet tested
- N/A = Not applicable for this SMD

Table IIIB. Hybrid level and element level test table.

	Radiation Test								
	Total Dose			Heavy Ion		Proton		Neutron	
	Low Dose Rate (LDR)	High Dose Rate (HDR)	ELDRS	SET (transient)	SEL (latch-up)	Low Energy	High Energy	SEE (upset)	Displacement Damage (DD)
CMOS IC	G	X (2 Mrad) (See 4.3.5.1.1)	G	(N)	G	(N)	(N)	(N)	G

NOTES:

- X = Radiation testing done (Level)
- G = Guaranteed by design or process.
- (N) = Not yet tested
- N/A = Not applicable for this SMD

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4.3.5.1 Radiation Hardness Assurance (RHA) inspection. RHA qualification is required for those devices with the RHA designator as specified herein. End-point electrical parameters for radiation hardness assurance (RHA) devices shall be specified in table II. Radiation testing will be in accordance with the qualifying activity (DLA Land and Maritime -VQ) approved plan and with MIL-PRF-38534, Appendix G.

- a. The hybrid device manufacturer shall establish procedures controlling component radiation testing, and shall establish radiation test plans used to implement component lot qualification during procurement. Test plans and test reports shall be filed and controlled in accordance with the manufacturer's configuration management system.
- b. The hybrid device manufacturer shall designate a RHA program manager to oversee component lot qualification, and to monitor design changes for continued compliance to RHA requirements.

4.3.5.1.1 Hybrid level RHA qualification. Hybrid level and element level testing are the same for the devices on this Standard Microcircuit Drawing (SMD) since the active element is accessible to the device leads for test.

4.3.5.1.1.1 Qualification by similarity. The devices on this (SMD) are considered similar for the purpose of RHA testing due to the device type 5962H1024301KXC being RHA tested for both of these (SMD's), therefore these device types on this SMD are qualified by similarity.

4.3.5.1.2 Element level qualification.

4.3.5.1.2.1 Total ionizing dose irradiation testing. A minimum of 5 biased devices of the active element used will be tested every wafer lot. These active elements will be tested at HDR in accordance with condition A of method 1019 of MIL-STD-883 to 2 Mrad(Si) to assure 1 Mrad(Si) for the device parameters as specified in table I herein.

4.3.5.1.2.1.1 Accelerated annealing test. Accelerated annealing tests shall be performed on all devices requiring a RHA level greater than 5k rads (Si). The post-anneal end-point electrical parameter limits shall be as specified in table I herein and shall be the pre-irradiation end-point electrical parameter limit at 25°C ±5°C. Testing shall be performed at initial qualification and after any design or process changes which may affect the RHA response of the device.

4.3.5.2 RHA Lot Acceptance. Each wafer lot of the active element shall be evaluated for acceptance in accordance with MIL-PRF-38534 and herein.

4.3.5.2.1 Total Ionizing Dose (TID). See paragraph 4.3.5.1.2.1 and 4.3.5.1.2.1.1 herein.

4.3.5.2.2 Enhanced Element Evaluation. Enhanced Element Evaluation per Table IV herein including 45 devices subjected to Group C2, 1000 hours life testing, is required only for those devices with the RHA designator as specified herein.

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Table IV. Enhanced Element Evaluation For Microcircuit Die.

Subgroup	Class K	Test	MIL-STD-883		Quantity (accept number)	Reference Paragraph <u>1/</u>
			Method	Condition		
2	X	Element visual	2010		100 percent	C.3.3.2
		Assembled into package as specified in 1.2.4 herein.			100 percent	
1	X	Element electrical			100 percent	C.3.3.1
3	X	Internal visual	2017		45(0)	C.5.5
4	X	Temperature cycling	1010	C	45(0) <u>2/</u>	C.3.3.3
	X	Constant acceleration	2001	3000g's, Y1 direction		C.5.6
	X	Burn-in	1015	160 hours minimum at +125°C		
	X	Interim electrical				C.3.3.4.3
	X	Burn-in	1015	160 hours minimum at +125°C		
	X	Post burn-in Final Electrical, Group A				C.5.10
	X	Steady-state life	1005	1000 hours minimum at +125°C		
	X	Final electrical				C.3.3.4.3
5	X	Wire bond evaluation	2011		10(0) wires or 20(1) wires	C.3.3.3 C.3.3.5
6	X	SEM	2018		See method 2018 of MIL-STD-883	C.3.3.6

1/ See MIL-PRF-38534.

2/ Die shall be traceable to the wafer and wafer lot. The sample size shall consist of a minimum of 3 die from each wafer and a minimum of 45 die from each wafer lot.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated as specified in MIL-PRF-38534.

6.4 Record of users. Military and industrial users shall inform DLA Land and Maritime when a system application requires configuration control and the applicable SMD. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime -VA, telephone (614) 692-8108.

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6.5 Comments. Comments on this drawing should be directed to DLA Land and Maritime -VA, Columbus, Ohio 43218-3990, or telephone (614) 692-1081.

6.6 Sources of supply. Sources of supply are listed in MIL-HDBK-103 and QML-38534. The vendors listed in MIL-HDBK-103 and QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DLA Land and Maritime -VA and have agreed to this drawing.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 13-10-01

Approved sources of supply for SMD 5962-12208 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38534 during the next revisions. MIL-HDBK-103 and QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revisions of MIL-HDBK-103 and QML-38534. DLA Land and Maritime maintains an online database of all current sources of supply at <http://www.landandmaritime.dla.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE	Vendor similar PIN <u>2/</u>
5962-1220801KXA	88379	RHD5928-201-2S
5962H1220801KXA	88379	RHD5928-901-2S
5962-1220801KXC	88379	RHD5928-201-1S
5962H1220801KXC	88379	RHD5928-901-1S
5962-1220802KXA	88379	RHD5929-201-2S
5962H1220802KXA	88379	RHD5929-901-2S
5962-1220802KXC	88379	RHD5929-201-1S
5962H1220802KXC	88379	RHD5929-901-1S
5962-1220803KXA	88379	RHD5927-201-2S
5962H1220803KXA	88379	RHD5927-901-2S
5962-1220803KXC	88379	RHD5927-201-1S
5962H1220803KXC	88379	RHD5927-901-1S

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

88379

Vendor name and address

Aeroflex Plainview Incorporated,
 (Aeroflex Microelectronic Solutions)
 35 South Service Road
 Plainview, NY 11803-4193

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.